

Technology Voucher Programme

Title (Reference)	: Bond Quotation App System Revamp Project (TVP/0980/17) 報價手機應用程式及後台提升 (TVP/0980/17)
Implementation Schedule (dd/mm/yyyy)	: 21/03/2018 - 29/06/2018
Total Approved Amount	: HK\$165,333.00
Project Coordinator	: Ms Wai-ling LEE / 李慧玲女士 Director, DC Square Limited Address: Flat D, 5/F, Blk 2, The Arcadia, 8 Forfar Road, Kowloon City, Hong Kong Tel: 852-5540 8905 Fax: - Email: ask@bondconnect.com.hk
Applicant Enterprise	: DC Square Limited
Proposed Technological Solution(s)	: <ul style="list-style-type: none"> • Others: Bond Quotation Information App with Backend System • 其他: Bond Quotation Information App with Backend System

All information above is provided by the company concerned. Please contact the company for more information.

Authorized Signature with
Company Chop of Applicant
Enterprise

: _____

Name of Signatory

: Ms. LEE, Wai Ling

Position

: Director

Applicant Enterprise

: DC Square Limited

Date

: 20 March 2018